



#### Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Types up to 1000 V  $V_{RRM}$
- Ideal for printed circuit board
- High surge current capability
- High temperature soldering guaranteed: 250°C/ 10 seconds, 0.375(9.5mm) lead length
- Glass passivated chip junction
- High case dielectric strength

GBL Package



#### Mechanical Data

Case: Molded plastic body over passivated junctions

Weight: 0.071 oz, 2 g

Mounting position: Any

Terminals: Plated leads, solderable per MIL-STD-750

Method 2026 guaranteed

#### Maximum ratings, at $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	G2SB06	G2SB08	G2SB10	Unit
Repetitive peak reverse voltage	$V_{RRM}$		600	800	1000	V
RMS reverse voltage	$V_{RMS}$		420	560	700	V
DC blocking voltage	$V_{DC}$		600	800	1000	V
Continuous forward current	$I_F$	$T_C \leq 25\text{ }^\circ\text{C}$	2	2	2	A
Surge non-repetitive forward current, Half Sine Wave	$I_{FSM}$	$T_C = 25\text{ }^\circ\text{C}$ , $t_p = 8.3\text{ ms}$	80	80	80	A
Operating temperature	$T_J$		-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$
Storage temperature	$T_{stg}$		-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$

#### Electrical characteristics, at $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	G2SB06	G2SB08	G2SB10	Unit
Diode forward voltage	$V_F$	$I_F = 1\text{ A}$ , $T_J = 25\text{ }^\circ\text{C}$	1.05	1.05	1.05	V
Reverse current	$I_R$	$V_R = 50\text{ V}$ , $T_J = 25\text{ }^\circ\text{C}$	5	5	5	$\mu\text{A}$
		$V_R = 50\text{ V}$ , $T_J = 125\text{ }^\circ\text{C}$	500	500	500	

#### Thermal characteristics

Parameter	Symbol	Conditions	G2SB06	G2SB08	G2SB10	Unit
Thermal resistance, junction - case	$R_{\theta JA}$		40.0	40.0	40.0	$^\circ\text{C/W}$
	$R_{\theta JL}$		12.0	12.0	12.0	

